

# NTMS7N03R2G

## MOSFET – Power, N-Channel, SOIC-8

7 A, 30 V

### Features

- Ultra Low  $R_{DS(on)}$
- Higher Efficiency Extending Battery Life
- Logic Level Gate Drive
- Miniature SOIC-8 Surface Mount Package
- Avalanche Energy Specified
- $I_{DSS}$  Specified at Elevated Temperature
- This is a Pb-Free Device

### Typical Applications

- DC-DC Converters
- Power Management
- Motor Controls
- Inductive Loads
- Replaces MMSF7N03HD, MMSF7N03Z, and MMSF5N03HD in Many Applications



ON Semiconductor®

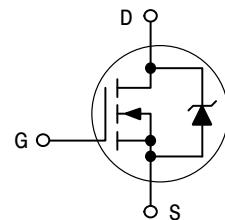
[www.onsemi.com](http://www.onsemi.com)

7 AMPERES

30 VOLTS

$R_{DS(on)} = 23 \text{ m}\Omega$

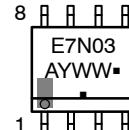
### N-Channel



### MARKING DIAGRAM



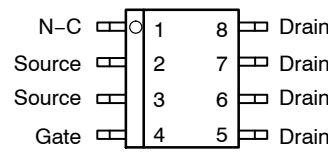
SOIC-8  
CASE 751  
STYLE 13



A = Assembly Location  
Y = Year  
WW = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### PIN ASSIGNMENT



Top View

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# NTMS7N03R2G

## MAXIMUM RATINGS (T<sub>C</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	30	Vdc
Drain-to-Gate Voltage (R <sub>GS</sub> = 1.0 MΩ)	V <sub>DGR</sub>	30	Vdc
Gate-to-Source Voltage – Continuous	V <sub>GS</sub>	±20	Vdc
Thermal Resistance, Junction-to-Ambient (Note 1)	R <sub>θJA</sub>	50	°C/W
Total Power Dissipation @ T <sub>A</sub> = 25°C	P <sub>D</sub>	2.5	W
Drain Current – Continuous @ T <sub>A</sub> = 25°C – Continuous @ T <sub>A</sub> = 70°C – Pulsed (Note 4)	I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	8.5 6.8 25	Adc Adc Apk
Thermal Resistance, Junction-to-Ambient (Note 2)	R <sub>θJA</sub>	85	°C/W
Total Power Dissipation @ T <sub>A</sub> = 25°C	P <sub>D</sub>	1.47	W
Drain Current – Continuous @ T <sub>A</sub> = 25°C – Continuous @ T <sub>A</sub> = 70°C – Pulsed (Note 4)	I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	6.5 5.2 18	Adc Adc Apk
Thermal Resistance, Junction-to-Ambient (Note 3)	R <sub>θJA</sub>	156	°C/W
Total Power Dissipation @ T <sub>A</sub> = 25°C	P <sub>D</sub>	0.8	W
Drain Current – Continuous @ T <sub>A</sub> = 25°C – Continuous @ T <sub>A</sub> = 70°C – Pulsed (Note 4)	I <sub>D</sub> I <sub>D</sub> I <sub>DM</sub>	4.8 3.8 14	Adc Adc Apk
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	–55 to +150	°C
Single Pulse Drain-to-Source Avalanche Energy – Starting T <sub>J</sub> = 25°C (V <sub>DD</sub> = 30 Vdc, V <sub>GS</sub> = 10 Vdc, Peak I <sub>L</sub> = 12 Apk, L = 4.0 mH, R <sub>G</sub> = 25 Ω)	E <sub>AS</sub>	288	mJ

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. 2 in. Sq. FR-4 PCB mounting, (2 oz. Cu 0.06 in. thick single sided), 10 Sec. Max.
2. 2 in. Sq. FR-4 PCB mounting, (2 oz. Cu 0.06 in. thick single sided), t = steady state.
3. Minimum FR4 or G10 PCB, t = steady state.
4. Pulse test: Pulse Width = 300 μs, Duty Cycle = 2%.

## ATTRIBUTES

Characteristics	Value
ESD Protection	Human Body Model Machine Model Charged Device Model

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTMS7N03R2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NTMS7N03R2G

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Drain-to-Source Breakdown Voltage (Notes 5 and 7) ( $V_{GS} = 0 \text{ Vdc}$ , $I_D = 0.25 \text{ mA}$ ) Temperature Coefficient (Positive)	$V_{(BR)DSS}$	30 –	– 41	– –	Vdc mV/°C
Zero Gate Voltage Drain Current ( $V_{DS} = 30 \text{ Vdc}$ , $V_{GS} = 0 \text{ Vdc}$ ) ( $V_{DS} = 30 \text{ Vdc}$ , $V_{GS} = 0 \text{ Vdc}$ , $T_J = 125^\circ\text{C}$ )	$I_{DSS}$	– –	0.02 –	1.0 10	$\mu\text{A}$
Gate-Body Leakage Current ( $V_{GS} = \pm 20 \text{ Vdc}$ , $V_{DS} = 0$ )	$I_{GSS}$	–	–	100	nA

## ON CHARACTERISTICS

Gate Threshold Voltage (Note 5) ( $V_{DS} = V_{GS}$ , $I_D = 0.25 \text{ mA}$ ) Threshold Temperature Coefficient (Negative)	$V_{GS(\text{th})}$	1.0 –	1.6 4.0	3.0 –	Vdc mV/°C
Static Drain-to-Source On-Resistance (Notes 5 and 7) ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 7.0 \text{ mA}$ ) ( $V_{GS} = 4.5 \text{ Vdc}$ , $I_D = 3.5 \text{ mA}$ )	$R_{DS(\text{on})}$	– –	18.6 23.5	23 28	$\text{m}\Omega$
Drain-to-Source On-Voltage ( $V_{GS} = 10 \text{ Vdc}$ , $I_D = 5.0 \text{ mA}$ ) (Notes 5 and 7)	$V_{DS(\text{on})}$	–	93	115	mV
Forward Transconductance ( $V_{DS} = 15 \text{ Vdc}$ , $I_D = 2.0 \text{ mA}$ ) (Note 5)	$g_{FS}$	3.0	13	–	Mhos

## DYNAMIC CHARACTERISTICS

Input Capacitance	$(V_{DS} = 25 \text{ Vdc}$ , $V_{GS} = 0 \text{ Vdc}$ , $f = 1.0 \text{ MHz}$ )	$C_{iss}$	–	1064	1190	pF
Output Capacitance		$C_{oss}$	–	300	490	
Transfer Capacitance		$C_{rss}$	–	94	120	

## SWITCHING CHARACTERISTICS (Note 6)

Turn-On Delay Time	$(V_{DD} = 10 \text{ Vdc}$ , $I_D = 5.0 \text{ mA}$ , $V_{GS} = 4.5 \text{ Vdc}$ , $R_G = 9.1 \Omega$ ) (Note 5)	$t_{d(\text{on})}$	–	15	30	ns
Rise Time		$t_r$	–	71	185	
Turn-Off Delay Time		$t_{d(\text{off})}$	–	27	70	
Fall Time		$t_f$	–	38	80	
Turn-On Delay Time	$(V_{DD} = 10 \text{ Vdc}$ , $I_D = 5.0 \text{ mA}$ , $V_{GS} = 10 \text{ Vdc}$ , $R_G = 9.1 \Omega$ ) (Note 5)	$t_{d(\text{on})}$	–	8.0	–	
Rise Time		$t_r$	–	38	–	
Turn-Off Delay Time		$t_{d(\text{off})}$	–	33	–	
Fall Time		$t_f$	–	49	–	
Gate Charge	$(V_{DS} = 16 \text{ Vdc}$ , $I_D = 5.0 \text{ mA}$ , $V_{GS} = 10 \text{ Vdc}$ ) (Note 5)	$Q_T$	–	26	43	nC
		$Q_1$	–	3.1	–	
		$Q_2$	–	6.0	–	

## SOURCE-DRAIN DIODE CHARACTERISTICS

Forward On-Voltage (Note 5)	$(I_S = 7.0 \text{ mA}$ , $V_{GS} = 0 \text{ Vdc}$ ) (Note 5) ( $I_S = 7.0 \text{ mA}$ , $V_{GS} = 0 \text{ Vdc}$ , $T_J = 125^\circ\text{C}$ )	$V_{SD}$	– –	0.82 0.67	1.1	Vdc
Reverse Recovery Time	$(I_S = 7.0 \text{ mA}$ , $V_{GS} = 0 \text{ Vdc}$ , $dI_S/dt = 100 \text{ A}/\mu\text{s}$ ) (Note 5)	$t_{rr}$	–	27	–	ns
		$t_a$	–	15	–	
		$t_b$	–	11.5	–	
Reverse Recovery Stored Charge		$Q_{RR}$	–	0.02	–	$\mu\text{C}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
6. Switching characteristics are independent of operating junction temperature.
7. Reflects Typical Values.

$$Cpk = \left| \frac{\text{Max limit} - \text{Typ}}{3 \times \Sigma} \right|$$

## TYPICAL ELECTRICAL CHARACTERISTICS

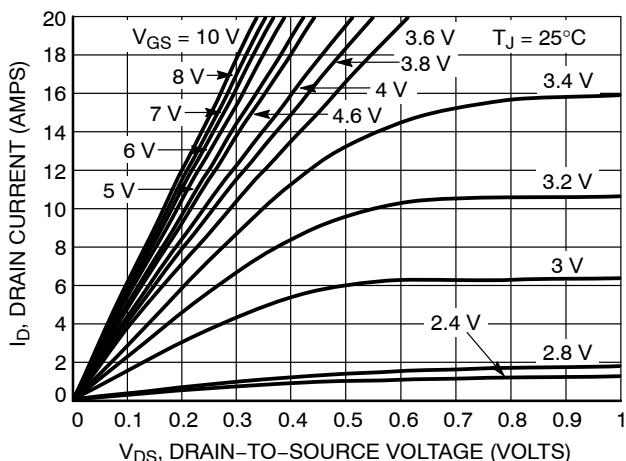


Figure 1. On-Region Characteristics

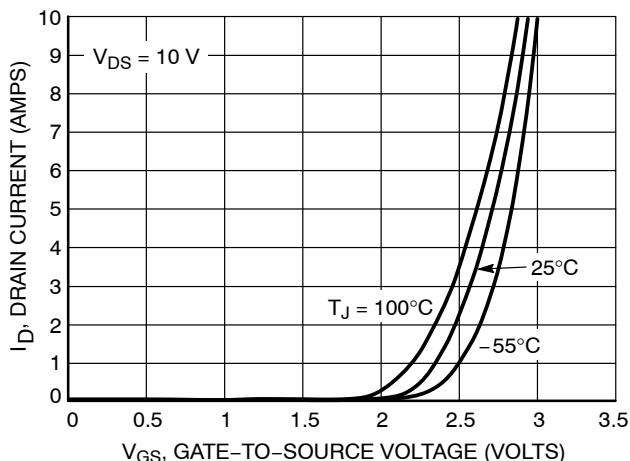


Figure 2. Transfer Characteristics

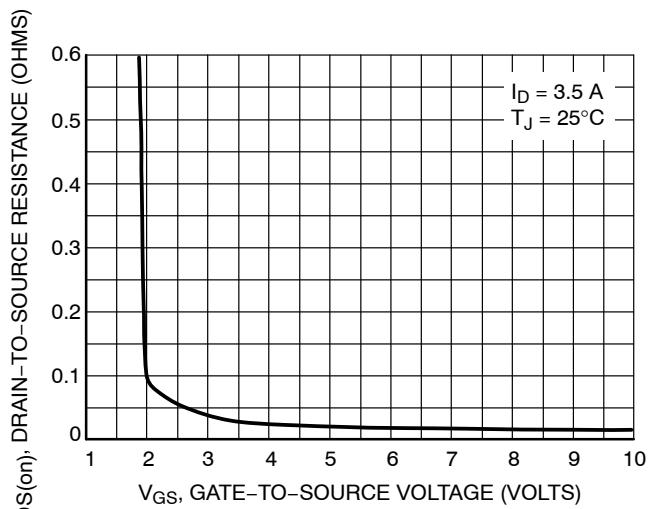


Figure 3. On-Resistance versus Gate-to-Source Voltage

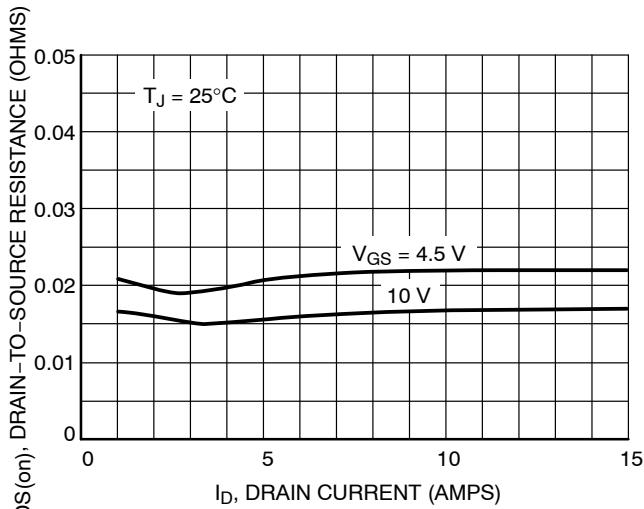


Figure 4. On-Resistance versus Drain Current and Gate Voltage

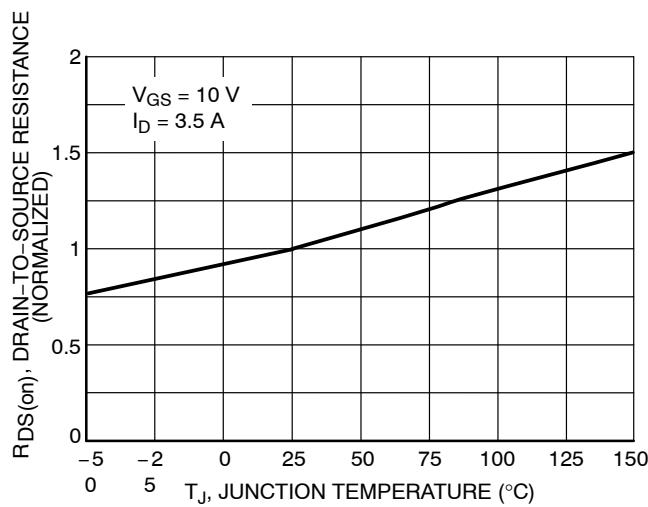


Figure 5. On-Resistance Variation with Temperature

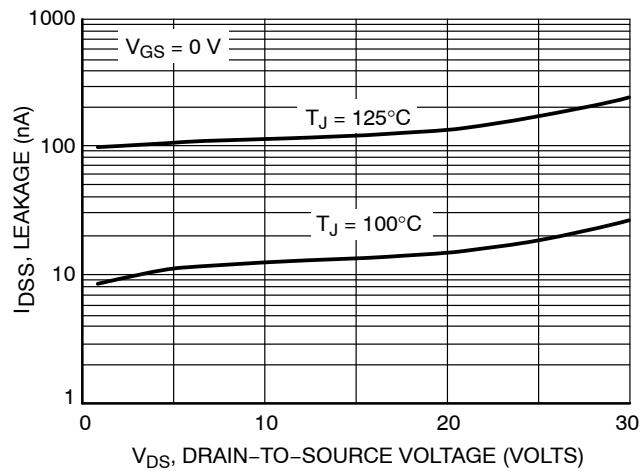


Figure 6. Drain-To-Source Leakage Current versus Voltage

## POWER MOSFET SWITCHING

Switching behavior is most easily modeled and predicted by recognizing that the power MOSFET is charge controlled. The lengths of various switching intervals ( $\Delta t$ ) are determined by how fast the FET input capacitance can be charged by current from the generator.

The published capacitance data is difficult to use for calculating rise and fall because drain-gate capacitance varies greatly with applied voltage. Accordingly, gate charge data is used. In most cases, a satisfactory estimate of average input current ( $I_{G(AV)}$ ) can be made from a rudimentary analysis of the drive circuit so that

$$t = Q/I_{G(AV)}$$

During the rise and fall time interval when switching a resistive load,  $V_{GS}$  remains virtually constant at a level known as the plateau voltage,  $V_{GSP}$ . Therefore, rise and fall times may be approximated by the following:

$$t_r = Q_2 \times R_G / (V_{GG} - V_{GSP})$$

$$t_f = Q_2 \times R_G / V_{GSP}$$

where

$V_{GG}$  = the gate drive voltage, which varies from zero to  $V_{GG}$

$R_G$  = the gate drive resistance

and  $Q_2$  and  $V_{GSP}$  are read from the gate charge curve.

During the turn-on and turn-off delay times, gate current is not constant. The simplest calculation uses appropriate values from the capacitance curves in a standard equation for voltage change in an RC network. The equations are:

$$t_{d(on)} = R_G C_{iss} \ln [V_{GG}/(V_{GG} - V_{GSP})]$$

$$t_{d(off)} = R_G C_{iss} \ln (V_{GG}/V_{GSP})$$

The capacitance ( $C_{iss}$ ) is read from the capacitance curve at a voltage corresponding to the off-state condition when calculating  $t_{d(on)}$  and is read at a voltage corresponding to the on-state when calculating  $t_{d(off)}$ .

At high switching speeds, parasitic circuit elements complicate the analysis. The inductance of the MOSFET source lead, inside the package and in the circuit wiring which is common to both the drain and gate current paths, produces a voltage at the source which reduces the gate drive current. The voltage is determined by  $L_{di}/dt$ , but since  $di/dt$  is a function of drain current, the mathematical solution is complex. The MOSFET output capacitance also complicates the mathematics. And finally, MOSFETs have finite internal gate resistance which effectively adds to the resistance of the driving source, but the internal resistance is difficult to measure and, consequently, is not specified.

The resistive switching time variation versus gate resistance (Figure 9) shows how typical switching performance is affected by the parasitic circuit elements. If the parasitics were not present, the slope of the curves would maintain a value of unity regardless of the switching speed. The circuit used to obtain the data is constructed to minimize common inductance in the drain and gate circuit loops and is believed readily achievable with board mounted components. Most power electronic loads are inductive; the data in the figure is taken with a resistive load, which approximates an optimally snubbed inductive load. Power MOSFETs may be safely operated into an inductive load; however, snubbing reduces switching losses.

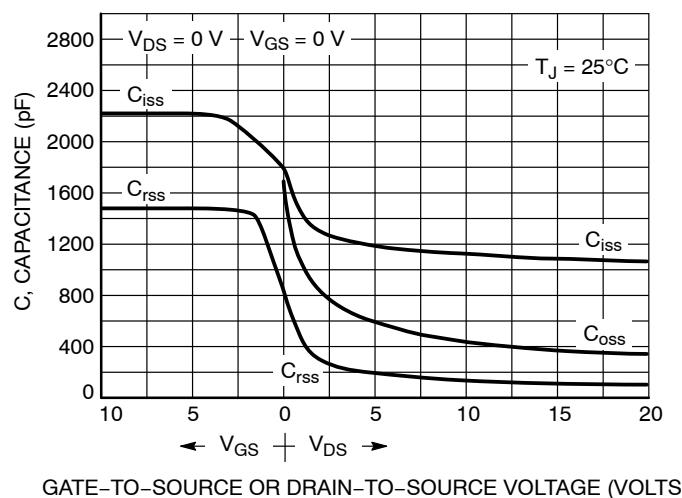
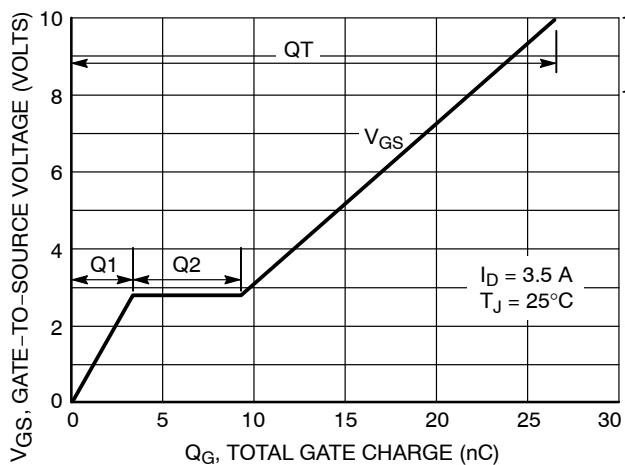
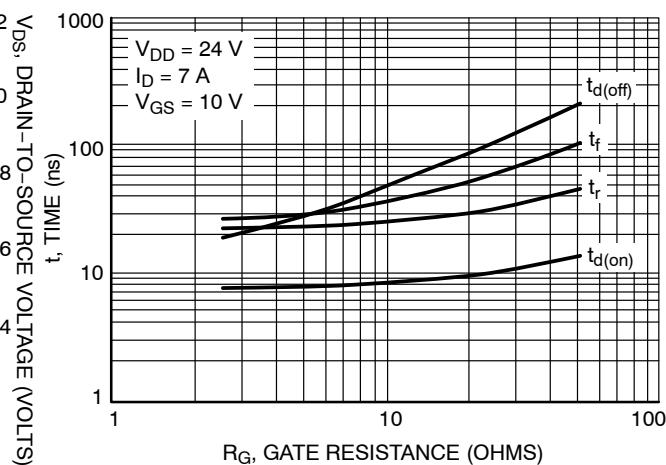


Figure 7. Capacitance Variation



**Figure 8. Gate-To-Source and Drain-To-Source Voltage versus Total Charge**



**Figure 9. Resistive Switching Time Variation versus Gate Resistance**

## DRAIN-TO-SOURCE DIODE CHARACTERISTICS

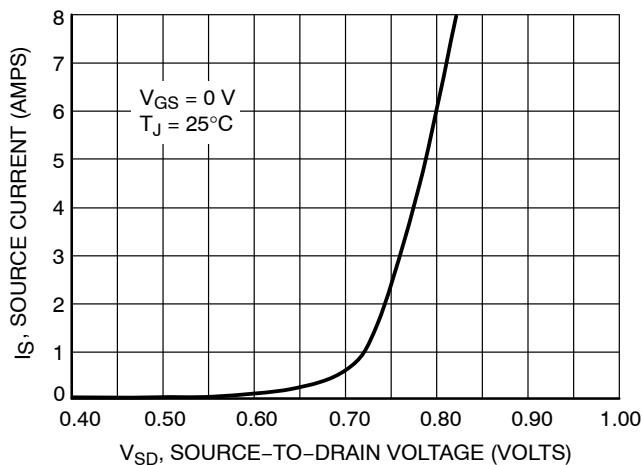
The switching characteristics of a MOSFET body diode are very important in systems using it as a freewheeling or commutating diode. Of particular interest are the reverse recovery characteristics which play a major role in determining switching losses, radiated noise, EMI and RFI.

System switching losses are largely due to the nature of the body diode itself. The body diode is a minority carrier device, therefore it has a finite reverse recovery time,  $t_{rr}$ , due to the storage of minority carrier charge,  $Q_{RR}$ , as shown in the typical reverse recovery wave form of Figure 15. It is this stored charge that, when cleared from the diode, passes through a potential and defines an energy loss. Obviously, repeatedly forcing the diode through reverse recovery further increases switching losses. Therefore, one would like a diode with short  $t_{rr}$  and low  $Q_{RR}$  specifications to minimize these losses.

The abruptness of diode reverse recovery effects the amount of radiated noise, voltage spikes, and current ringing. The mechanisms at work are finite irremovable circuit parasitic inductances and capacitances acted upon by

high  $di/dts$ . The diode's negative  $di/dt$  during  $t_a$  is directly controlled by the device clearing the stored charge. However, the positive  $di/dt$  during  $t_b$  is an uncontrollable diode characteristic and is usually the culprit that induces current ringing. Therefore, when comparing diodes, the ratio of  $t_b/t_a$  serves as a good indicator of recovery abruptness and thus gives a comparative estimate of probable noise generated. A ratio of 1 is considered ideal and values less than 0.5 are considered snappy.

Compared to ON Semiconductor standard cell density low voltage MOSFETs, high cell density MOSFET diodes are faster (shorter  $t_{rr}$ ), have less stored charge and a softer reverse recovery characteristic. The softness advantage of the high cell density diode means they can be forced through reverse recovery at a higher  $di/dt$  than a standard cell MOSFET diode without increasing the current ringing or the noise generated. In addition, power dissipation incurred from switching the diode will be less due to the shorter recovery time and lower switching losses.



**Figure 10. Diode Forward Voltage versus Current**

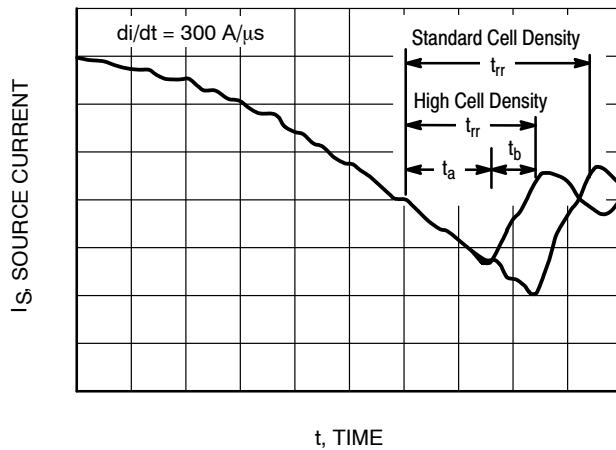


Figure 11. Reverse Recovery Time ( $t_{rr}$ )

## SAFE OPERATING AREA

The Forward Biased Safe Operating Area curves define the maximum simultaneous drain-to-source voltage and drain current that a transistor can handle safely when it is forward biased. Curves are based upon maximum peak junction temperature and a case temperature ( $T_C$ ) of 25°C. Peak repetitive pulsed power limits are determined by using the thermal response data in conjunction with the procedures discussed in AN569, "Transient Thermal Resistance – General Data and Its Use."

Switching between the off-state and the on-state may traverse any load line provided neither rated peak current ( $I_{DM}$ ) nor rated voltage ( $V_{DSS}$ ) is exceeded, and that the transition time ( $t_r, t_f$ ) does not exceed 10  $\mu$ s. In addition the total power averaged over a complete switching cycle must not exceed  $(T_{J(MAX)} - T_C)/(R_{\theta JC})$ .

A power MOSFET designated E-FET can be safely used in switching circuits with unclamped inductive loads. For

reliable operation, the stored energy from circuit inductance dissipated in the transistor while in avalanche must be less than the rated limit and must be adjusted for operating conditions differing from those specified. Although industry practice is to rate in terms of energy, avalanche energy capability is not a constant. The energy rating decreases non-linearly with an increase of peak current in avalanche and peak junction temperature.

Although many E-FETs can withstand the stress of drain-to-source avalanche at currents up to rated pulsed current ( $I_{DM}$ ), the energy rating is specified at rated continuous current ( $I_D$ ), in accordance with industry custom. The energy rating must be derated for temperature as shown in the accompanying graph (Figure 13). Maximum energy at currents below rated continuous  $I_D$  can safely be assumed to equal the values indicated.

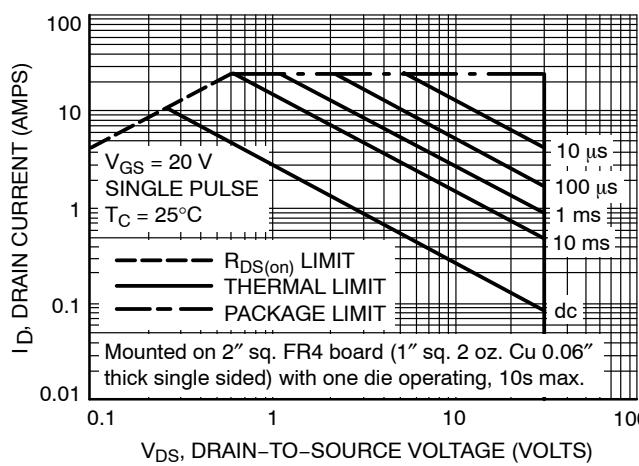


Figure 12. Maximum Rated Forward Biased Safe Operating Area

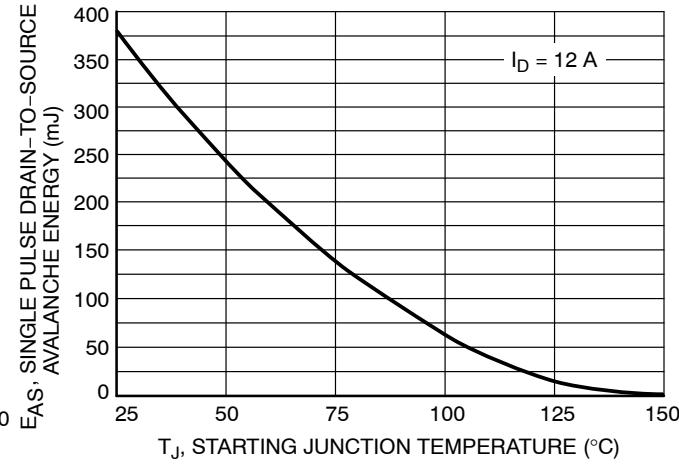


Figure 13. Maximum Avalanche Energy versus Starting Junction Temperature

## TYPICAL ELECTRICAL CHARACTERISTICS

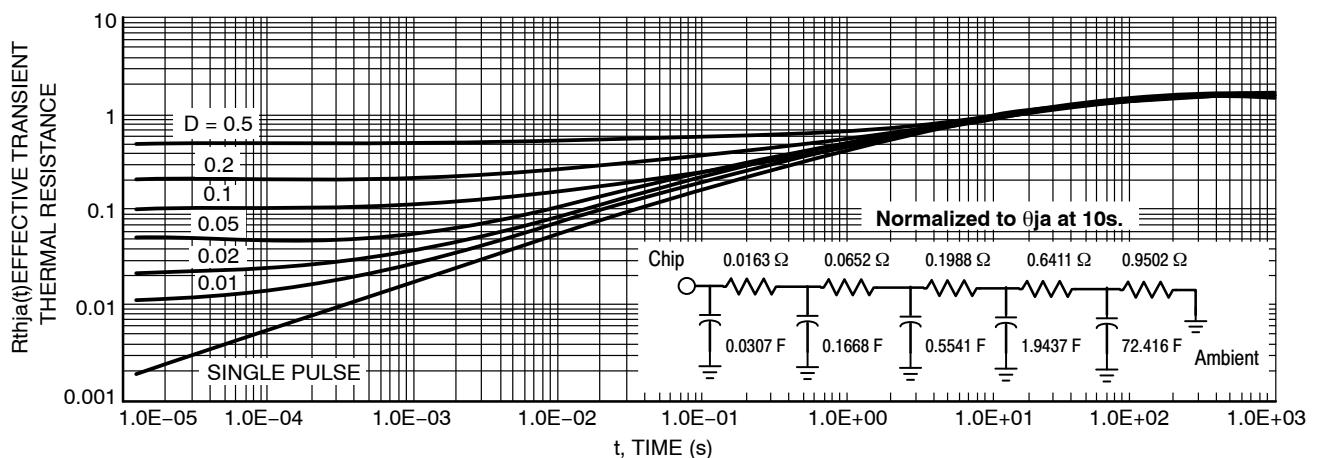


Figure 14. Thermal Response

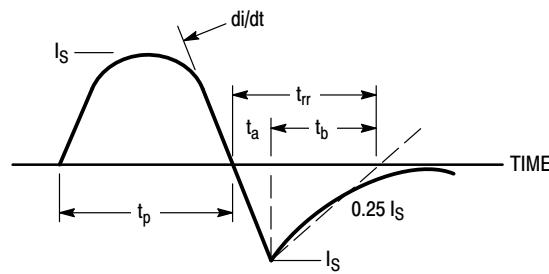


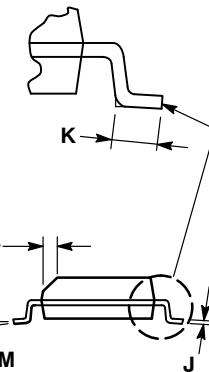
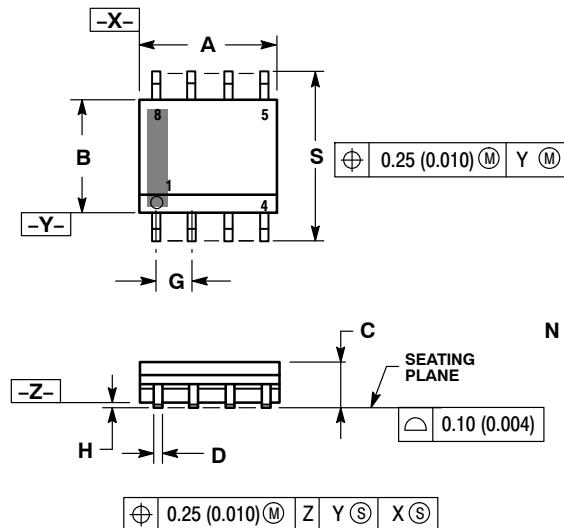
Figure 15. Diode Reverse Recovery Waveform



SCALE 1:1

SOIC-8 NB  
CASE 751-07  
ISSUE AK

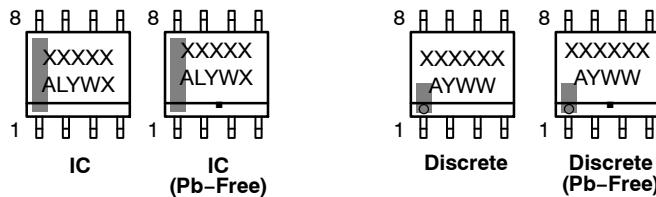
DATE 16 FEB 2011



## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

GENERIC  
MARKING DIAGRAM\*

XXXXXX = Specific Device Code  
 A = Assembly Location  
 L = Wafer Lot  
 Y = Year  
 W = Work Week  
 ■ = Pb-Free Package

XXXXXX = Specific Device Code  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42564B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOIC-8 NB	PAGE 1 OF 2

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**SOIC-8 NB**  
**CASE 751-07**  
**ISSUE AK**

DATE 16 FEB 2011

STYLE 1: PIN 1. Emitter 2. Collector 3. Collector 4. Emitter 5. Emitter 6. Base 7. Base 8. Emitter	STYLE 2: PIN 1. Collector, Die #1 2. Collector, #1 3. Collector, #2 4. Collector, #2 5. Base, #2 6. Emitter, #2 7. Base, #1 8. Emitter, #1	STYLE 3: PIN 1. Drain, Die #1 2. Drain, #1 3. Drain, #2 4. Drain, #2 5. Gate, #2 6. Source, #2 7. Gate, #1 8. Source, #1	STYLE 4: PIN 1. Anode 2. Anode 3. Anode 4. Anode 5. Anode 6. Anode 7. Anode 8. Common Cathode
STYLE 5: PIN 1. Drain 2. Drain 3. Drain 4. Drain 5. Gate 6. Gate 7. Source 8. Source	STYLE 6: PIN 1. Source 2. Drain 3. Drain 4. Source 5. Source 6. Gate 7. Gate 8. Source	STYLE 7: PIN 1. Input 2. External Bypass 3. Third Stage Source 4. Ground 5. Drain 6. Gate 3 7. Second Stage Vd 8. First Stage Vd	STYLE 8: PIN 1. Collector, Die #1 2. Base, #1 3. Base, #2 4. Collector, #2 5. Collector, #2 6. Emitter, #2 7. Emitter, #1 8. Collector, #1
STYLE 9: PIN 1. Emitter, Common 2. Collector, Die #1 3. Collector, Die #2 4. Emitter, Common 5. Emitter, Common 6. Base, Die #2 7. Base, Die #1 8. Emitter, Common	STYLE 10: PIN 1. Ground 2. Bias 1 3. Output 4. Ground 5. Ground 6. Bias 2 7. Input 8. Ground	STYLE 11: PIN 1. Source 1 2. Gate 1 3. Source 2 4. Gate 2 5. Drain 2 6. Drain 2 7. Drain 1 8. Drain 1	STYLE 12: PIN 1. Source 2. Source 3. Source 4. Gate 5. Drain 6. Drain 7. Drain 8. Drain
STYLE 13: PIN 1. N.C. 2. Source 3. Source 4. Gate 5. Drain 6. Drain 7. Drain 8. Drain	STYLE 14: PIN 1. N-Source 2. N-Gate 3. P-Source 4. P-Gate 5. P-Drain 6. P-Drain 7. N-Drain 8. N-Drain	STYLE 15: PIN 1. Anode 1 2. Anode 1 3. Anode 1 4. Anode 1 5. Cathode, Common 6. Cathode, Common 7. Cathode, Common 8. Cathode, Common	STYLE 16: PIN 1. Emitter, Die #1 2. Base, Die #1 3. Emitter, Die #2 4. Base, Die #2 5. Collector, Die #2 6. Collector, Die #2 7. Collector, Die #1 8. Collector, Die #1
STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC	STYLE 18: PIN 1. Anode 2. Anode 3. Source 4. Gate 5. Drain 6. Drain 7. Cathode 8. Cathode	STYLE 19: PIN 1. Source 1 2. Gate 1 3. Source 2 4. Gate 2 5. Drain 2 6. Mirror 2 7. Drain 1 8. Mirror 1	STYLE 20: PIN 1. Source (N) 2. Gate (N) 3. Source (P) 4. Gate (P) 5. Drain 6. Drain 7. Drain 8. Drain
STYLE 21: PIN 1. Cathode 1 2. Cathode 2 3. Cathode 3 4. Cathode 4 5. Cathode 5 6. Common Anode 7. Common Anode 8. Cathode 6	STYLE 22: PIN 1. I/O Line 1 2. Common Cathode/VCC 3. Common Cathode/VCC 4. I/O Line 3 5. Common Anode/GND 6. I/O Line 4 7. I/O Line 5 8. Common Anode/GND	STYLE 23: PIN 1. Line 1 IN 2. Common Anode/GND 3. Common Anode/GND 4. Line 2 IN 5. Line 2 OUT 6. Common Anode/GND 7. Common Anode/GND 8. Line 1 OUT	STYLE 24: PIN 1. Base 2. Emitter 3. Collector/Anode 4. Collector/Anode 5. Cathode 6. Cathode 7. Collector/Anode 8. Collector/Anode
STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT	STYLE 26: PIN 1. GND 2. dv/dt 3. Enable 4. ILIMIT 5. Source 6. Source 7. Source 8. VCC	STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN	STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBUCK 7. VBUCK 8. VIN
STYLE 29: PIN 1. Base, Die #1 2. Emitter, #1 3. Base, #2 4. Emitter, #2 5. Collector, #2 6. Collector, #2 7. Collector, #1 8. Collector, #1	STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1		

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